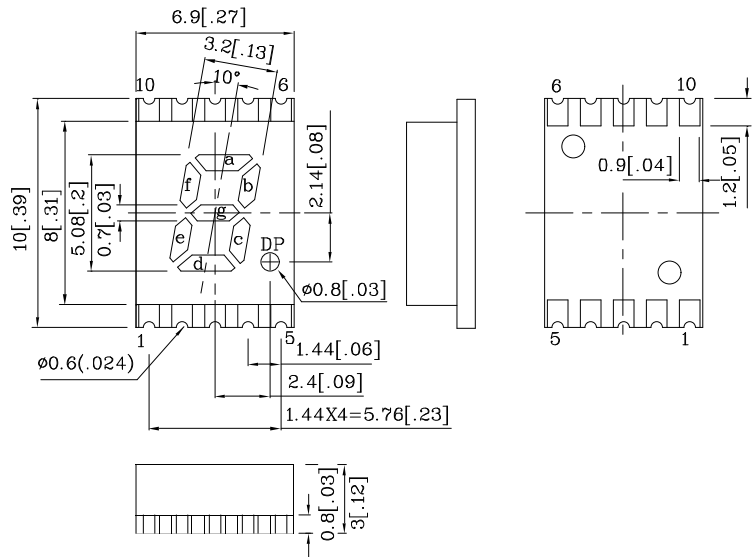
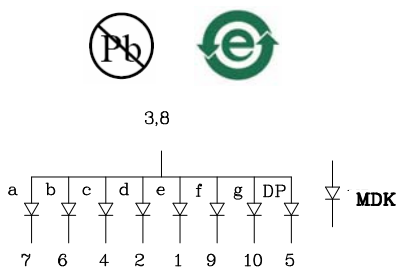


Features

- 0.21 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- GRAY FACE, WHITE SEGMENT.
- PACKAGE : 650 PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



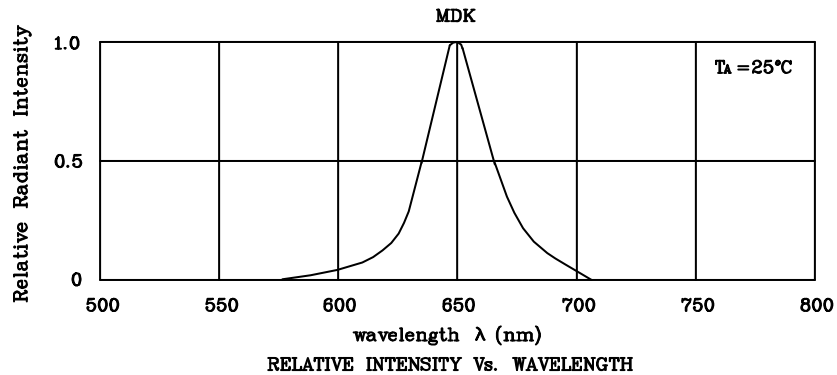
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. The gap between the reflector and PCB shall not exceed 0.25mm.
4. Specifications are subject to change without notice.

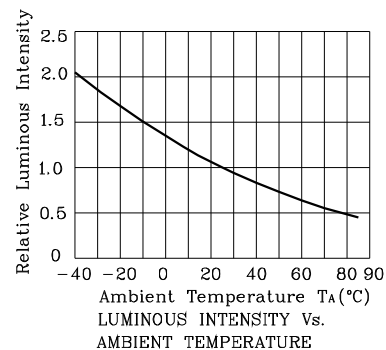
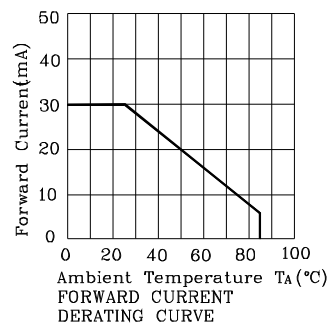
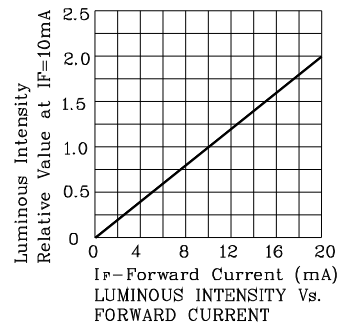
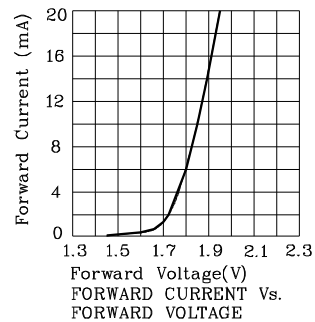
Absolute Maximum Ratings (TA=25°C)		MDK (InGaAlP)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	185	mA
Power Dissipation	PT	75	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	

Operating Characteristics (TA=25°C)		MDK (InGaAlP)	Unit
Forward Voltage (Typ.) (IF=10mA)	VF	1.85	V
Forward Voltage (Max.) (IF=10mA)	VF	2.5	V
Reverse Current (Max.) (VR=5V)	IR	10	uA
Wavelength of Peak Emission (Typ.) (IF=10mA)	λP	650	nm
Wavelength of Dominant Emission (Typ.) (IF=10mA)	λD	635	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=10mA)	$\Delta\lambda$	28	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	C	35	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity (IF=10mA) ucd	Wavelength nm λP	Description
			min.	typ.	
ZFMDK05A	Red	InGaAlP	8000	30390	650 Common Anode, Rt. Hand Decimal
Published Date : FEB 28, 2008					
Drawing No : SDSA5283					
V2					
Checked : Shin Chi					
P.1/4					



❖ **MDK**



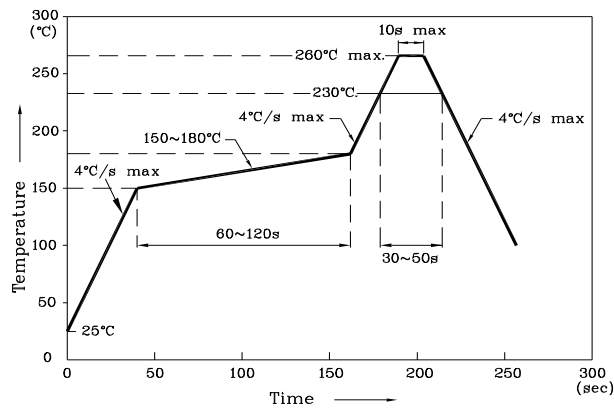
Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: $\pm 1\text{nm}$
2. Luminous Intensity / Luminous Flux: $\pm 15\%$
3. Forward Voltage: $\pm 0.1\text{V}$

Note: Accuracy may depend on the sorting parameters.

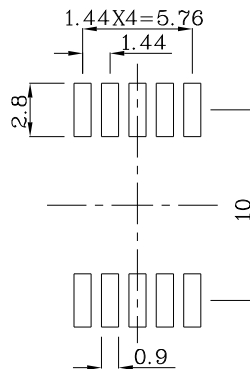
Reflow Soldering Profile For Lead-free SMT Process.



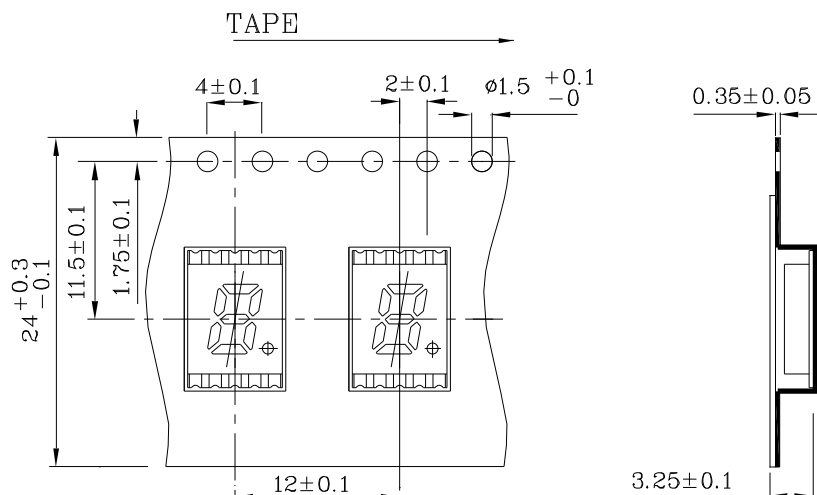
Notes:

- 1.Maximum soldering temperature should not exceed 260°C.
- 2.Recommended reflow temperature: 145°C~260°C.
- 3.Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm;Tolerance: ± 0.15)

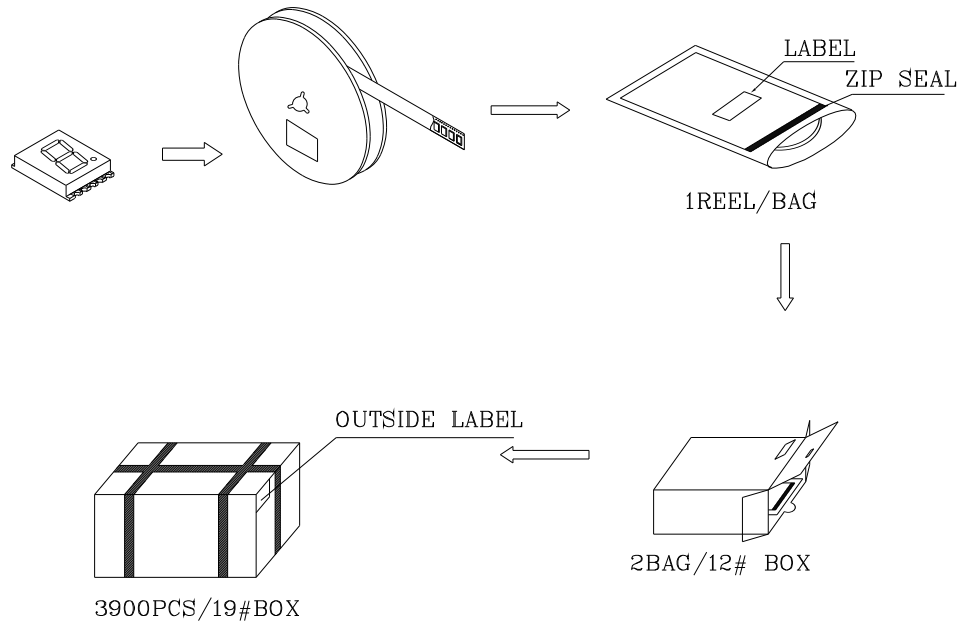


❖ Tape Specification (Units : mm)

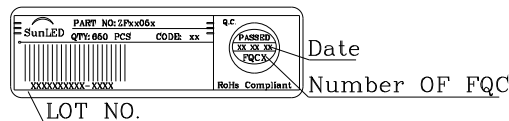


PACKING & LABEL SPECIFICATIONS

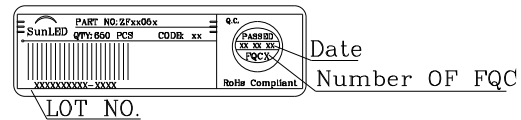
ZFMDK05A



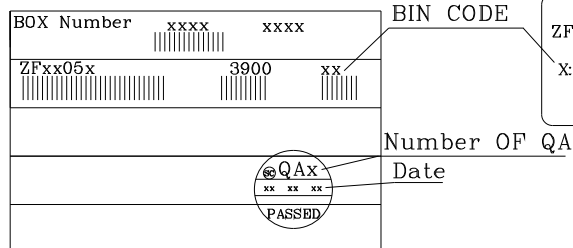
Inside LABEL Paste On The TAPE



Outside LABEL Paste On The BAG



Outside LABEL Paste On The 19#Box



Outside LABEL Paste On The 12#Box

